





Docket No. _JCLA6224_

Date: /2-/-2000

Page 1

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Ching-Yu Chang; I-Pien Wu For: HOT PLATE COOLING SYSTEM

Enclosed are:

\boxtimes	Specification	9	pages.
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Recordation Form Cover sheet with <u>2</u> pages assignment.

A certified copy of Taiwan Patent Application No. __ dated ___

SIGNED declaration and power of attorney.

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CLAIMS AS FILED										
FOR	NUMB	ER FII	ED	NUMBE	REXTRA	RATE	FEE			
Basic Fee						\$710.00	\$710.00			
Total Claims	14	_	20 =	= 0	×	\$18.00	\$0.00			
Independent Claims	2		3 =	= 0	×	\$80.00	\$0.00			
If application contains any multiple dependent claim (s), then add							\$0.00			
TOTAL FILING FEE						\$710.00				

A check in the amount of \$710.00 cover the filing fee is enclosed.

A check in the amount of \$40.00 to cover the assignment recording fee.

A duplicate copy of this sheet is enclosed.

Jiawei Huang

Registration No. 43,330



Compared to the first of the fi

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : JCLA6224

Applicant(s) : Ching-Yu Chang; I-Pien Wu

For : HOT PLATE COOLING SYSTEM

"Express Mail" : EL608225791US

Mailing Label No.

Date of Deposit : December 1, 2000

I hereby certify that the accompanying

Transmittal in Duplicate; Specification <u>9</u> pages, <u>2</u> sheets of drawings; **SIGNED** Declaration and Power of Attorney <u>2</u> pages; Recordation Form Cover Sheet and Assignment <u>3</u> pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Jiawei Huang